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METASURFACE

METASURFACE TECHNOLOGIES HOLDINGS LIMITED

元续科技控股有限公司

(Incorporated in Cayman Islands with limited liability)

(Stock code: 8637)

VOLUNTARY ANNOUNCEMENT BUSINESS UPDATE

This announcement is made by Metasurface Technologies Holdings Limited (the “**Company**”, and its subsidiaries, the “**Group**”) on a voluntary basis to keep shareholders and potential investors of the Company informed of the latest business development of the Group.

The board (the “**Board**”) of directors of the Company is pleased to announce the Group’s collaboration with a leading semiconductor original equipment manufacturer, in which the Group has been entrusted with the production of newly designed critical components for integration into advanced wafer fabrication equipment systems.

The appended press release contains further details.

By Order of the Board

Metasurface Technologies Holdings Limited

CHUA Chwee Lee (Cai Shuili)

Chairman, Chief Executive Officer and Executive Director

Singapore, 18 December 2024

As at the date of this announcement, the executive Directors of the Company are Dato’ Sri CHUA Chwee Lee (CAI Shuili), Ms. JEE Wee Jene and Mr. THNG Chong Kim; and the independent non-executive Directors are Mr. TAN Chek Kian, Mr. ANG Yong Sheng, Jonathan (HONG Yongsheng) and Mr. CHAN Yang Kang.

This announcement, for which the Directors collectively and individually accept full responsibility, includes particulars given in compliance with the Rules Governing the Listing of Securities on GEM of The Stock Exchange of Hong Kong Limited for the purpose of giving information with regard to the Company. The Directors, having made all reasonable enquiries, confirm that to the best of their knowledge and belief the information contained in this announcement is accurate and complete in all material respects and not misleading or deceptive, and there are no other matters the omission of which would make any statement herein or this announcement misleading.

This announcement is available for viewing on the website of the Company at www.metatechnologies.com.sg and the website of the Stock Exchange at www.hkexnews.hk.

APPENDIX

Metasurface Technologies Holdings Limited Announces Strategic Partnership with Leading Semiconductor OEM

New precision-engineered components to drive next-gen semiconductor manufacturing

Collaboration positions Metasurface as a key supplier for high-demand sub-180 nm wafer fab platforms

SINGAPORE and HONG KONG, Dec. 18, 2024/PRNewswire/— Metasurface Technologies Holdings Limited (HKG: 8637) (“**Metasurface**” or the “**Company**“, together with its subsidiaries, the “**Group**”), a provider of precision engineering services, is pleased to announce a significant collaboration with a leading semiconductor Original Equipment Manufacturer (OEM). The Group has been entrusted with the production of newly designed critical components for integration into advanced wafer fabrication equipment systems.



This partnership underscores the Group’s expertise in precision machining and its reputation as a trusted supplier in the semiconductor industry. The components include a high-precision wafer fabrication vacuum chamber and ancillary parts, all of which demand stringent manufacturing standards. The vacuum chamber, essential for inter-layer dielectric deposition — a pivotal process in semiconductor fabrication — requires exacting tolerances and zero-defect performance.

Key Highlights:

- **Advanced Manufacturing Excellence:** The vacuum chamber features a central channel port that must be machined with Geometric Dimensioning and Tolerancing (GD&T) exactness, maintaining micron-level tolerances in flatness and parallelism without secondary processing. The Group has developed customized precision tooling and employs advanced machining techniques to meet these rigorous specifications. Each component undergoes comprehensive quality control, including helium leak testing within ultra-high purity cleanroom environments, ensuring adherence to zero-defect standards critical for high-speed wafer processing.

- **Projected Growth and Industry Impact:** The semiconductor OEM anticipates increasing production volumes year-over-year for the next three years, indicating robust demand for these components. The Group's capacity to fulfil these escalating requirements positions it as a key supplier to one of the industry's most advanced production lines. These components will be integral to the OEM's new ultra-high productivity platform for sub-180 nm devices, facilitating the production of next-generation semiconductor chips. By enabling precise inter-layer dielectric deposition, this platform is set to drive innovation and efficiency in semiconductor manufacturing.

About the Group

Headquartered in Singapore, with production facilities in Singapore and Malaysia, the Group specializes in precision engineering services, including precision machining and precision welding. With over two decades of industry expertise and experience serving leading global customers, the Group is a trusted partner in delivering innovative solutions that meet the most stringent technical and commercial requirements. The Group is accredited with ISO 9001:2015 for quality management and ISO 14001:2015 for environmental management, reflecting its commitment to excellence and sustainability. Find out more at www.metatechnologies.com.sg.

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